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Kind regards,

Team Nexperia

PCMFXHDMI14S series

Common-mode EMI filter for differential channels with integrated ESD protection

Rev. 1 — 15 September 2016

Product data sheet

1. Product profile

1.1 General description

Common-mode ElectroMagnetic Interference (EMI) filters with integrated ElectroStatic Discharge (ESD) protection for one, two and three differential channels. The devices are designed to provide low insertion loss for differential high-speed signals on each channel while unwanted common-mode signals are attenuated.

Each differential channel incorporates two signal lines that are coupled by integrated coils. Diodes provide protection to downstream components from ESD voltages up to ± 15 kV on each signal line.

Table 1. Product overview

Type number	Number of channels	Package Name
PCMF1HDMI14S	1	WLCSP5
PCMF2HDMI14S	2	WLCSP10
PCMF3HDMI14S	3	WLCSP15

1.2 Features and benefits

- One, two and three differential channels common-mode EMI filters with integrated ESD protection
- ESD protection up to ± 15 kV contact discharge according to IEC 61000-4-2
- Superior common-mode suppression over a wide frequency range
- Superior RF performance compared to other integrated filters or discrete filters with external ESD protection
- Extremely high symmetry between line pairs
- Industry-standard Wafer Level Chip Scale Packages: WLCSP5, 10 and 15 for smaller footprint

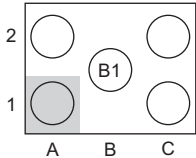
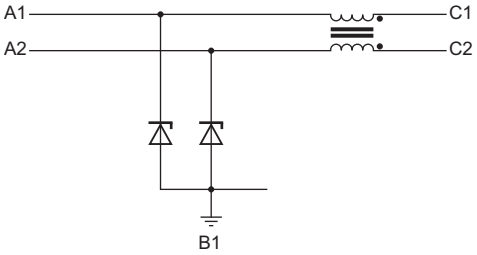
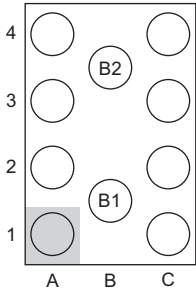
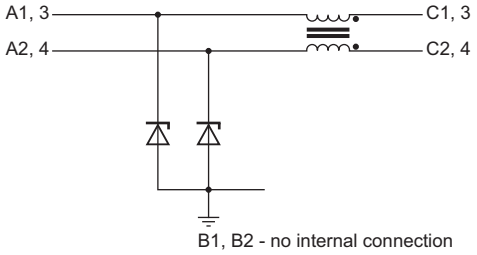
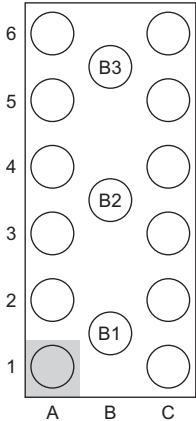
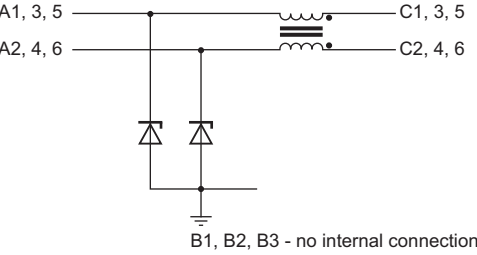
1.3 Applications

- Smartphone, cellular and cordless phone
- Tablet PC and Mobile Internet Device (MID)
- HDMI 1.4
- General-purpose EMI and Radio-Frequency Interference (RFI) filter and downstream ESD protection



2. Pinning information

Table 2. Pinning

Pin	Symbol	Description	Simplified outline	Graphic symbol
PCMF1HDMI14S (WLCSP5_2-1-2)				
A1	CH1_IN+	channel 1+, external	 <p>Transparent top view WLCSP5_2-1-2</p>	 <p style="text-align: right;">aaa-019784</p>
A2	CH1_IN-	channel 1-, external		
B1	GND_CH1	ground channel 1		
C1	CH1_OUT+	channel 1+, internal		
C2	CH1_OUT-	channel 1-, internal		
PCMF2HDMI14S (WLCSP10_4-2-4)				
A1	CH1_IN+	channel 1+, external	 <p>Transparent top view WLCSP10_4-2-4</p>	 <p style="text-align: right;">B1, B2 - no internal connection aaa-019785</p>
A2	CH1_IN-	channel 1-, external		
A3	CH2_IN+	channel 2+, external		
A4	CH2_IN-	channel 2-, external		
B1	GND_CH1	ground channel 1		
B2	GND_CH2	ground channel 2		
C1	CH1_OUT+	channel 1+, internal		
C2	CH1_OUT-	channel 1-, internal		
C3	CH2_OUT+	channel 2+, internal		
C4	CH2_OUT-	channel 2-, internal		
PCMF3HDMI14S (WLCSP15_6-3-6)				
A1	CH1_IN+	channel 1+, external	 <p>Transparent top view WLCSP15_6-3-6</p>	 <p style="text-align: right;">B1, B2, B3 - no internal connection aaa-019786</p>
A2	CH1_IN-	channel 1-, external		
A3	CH2_IN+	channel 2+, external		
A4	CH2_IN-	channel 2-, external		
A5	CH3_IN+	channel 3+, external		
A6	CH3_IN-	channel 3-, external		
B1	GND_CH1	ground channel 1		
B2	GND_CH2	ground channel 2		
B3	GND_CH3	ground channel 3		
C1	CH1_OUT+	channel 1+, internal		
C2	CH1_OUT-	channel 1-, internal		
C3	CH2_OUT+	channel 2+, internal		
C4	CH2_OUT-	channel 2-, internal		
C5	CH3_OUT+	channel 3+, internal		
C6	CH3_OUT-	channel 3-, internal		

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PCMF1HDMI14S	WLCSP5	wafer level chip-size package; 5 bumps (2-1-2)	PCMF1HDMI14S
PCMF2HDMI14S	WLCSP10	wafer level chip-size package; 10 bumps (4-2-4)	PCMF2HDMI14S
PCMF3HDMI14S	WLCSP15	wafer level chip-size package; 15 bumps (6-3-6)	PCMF3HDMI14S

4. Marking

Table 4. Marking codes

Type number	Marking code
PCMF1HDMI14S	PF1S
PCMF2HDMI14S	PF2S
PCMF3HDMI14S	PF3S

5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_I	input voltage		-0.5	5	V
V_{ESD}	electrostatic discharge voltage	IEC 61000-4-2, level 4; all input pins to ground			
		contact discharge	-15	15	kV
		air discharge	-15	15	kV
		IEC 61000-4-2, level 4; all output pins to ground			
		contact discharge	-2	2	kV
		air discharge	-2	2	kV
I_{PPM}	rated peak pulse current	$t_p = 8/20 \mu s$	-7	7	A
T_{stg}	storage temperature		-40	+125	°C
T_{amb}	ambient temperature		-40	+85	°C

6. Characteristics

6.1 Channel characteristics

Table 6. Channel characteristics

$T_{amb} = 25\text{ }^{\circ}\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{s(ch)}$	channel series resistance	single line; input to output	-	3	-	Ω
C_d	diode capacitance	$f = 1\text{ MHz}$; $V_I = 2.5\text{ V}$ [1]	-	0.25	-	pF
I_{RM}	reverse leakage current	per line; $V_I = 5\text{ V}$	-	-	100	nA
V_{BR}	breakdown voltage	$I_R = 1\text{ mA}$	6	9	-	V
V_F	forward voltage	$I_F = 10\text{ mA}$	-	0.8	-	V
V_{CL}	clamping voltage	TLP [2]				
		$I_{PP} = -16\text{ A}$	-	-3.7	-	V
		$I_{PP} = -8\text{ A}$	-	-2.5	-	V
		$I_{PP} = 8\text{ A}$	-	2.8	-	V
R_{dyn}	dynamic resistance	TLP [2]				
		positive transient	-	0.16	-	Ω
		negative transient	-	0.16	-	Ω
		surge [3]				
		positive transient	-	0.22	-	Ω
	negative transient	-	0.22	-	Ω	

[1] This parameter is guaranteed by design.

[2] 100 ns Transmission Line Pulse (TLP); 50 Ω ; pulser at 70 ns to 90 ns.

[3] According to IEC 61000-4-5 (8/20 μs).

6.2 Frequency characteristics

Table 7. Frequency characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Common mode: S_{21cc}						
α_{il}	insertion loss	[1]				
		$f = 800\text{ MHz}$	-	-12	-	dB
		$f = 1.7\text{ GHz}$	-	-21.5	-	dB
		$f = 3\text{ GHz}$	-	-31.5	-	dB
Differential mode: S_{21dd}						
α_{il}	insertion loss	$f = 1\text{ MHz}$ [1]	-	0.3	-	dB
f_{-3dB}	cut-off frequency	[1]	-	6	-	GHz

[1] Normalized to attenuation at 1 MHz.

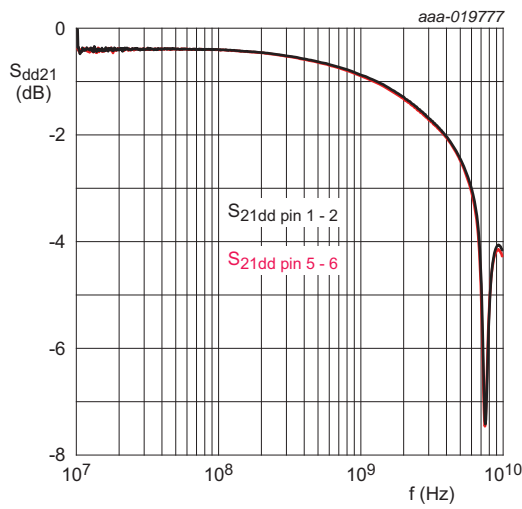


Fig 1. Differential-mode insertion loss; typical values

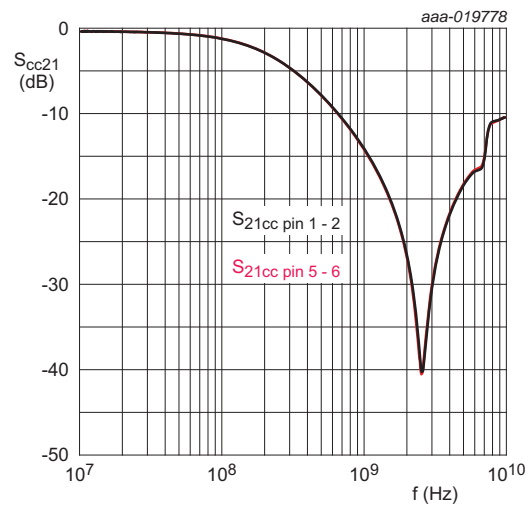


Fig 2. Common-mode insertion loss; typical values

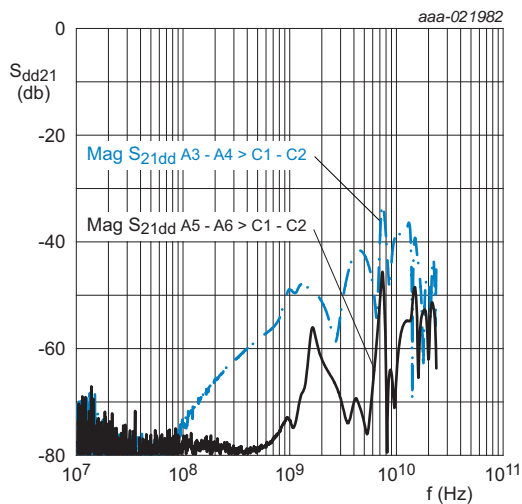


Fig 3. Differential crosstalk; typical values

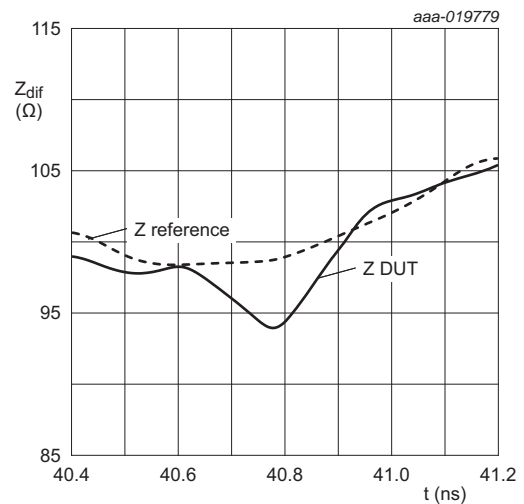
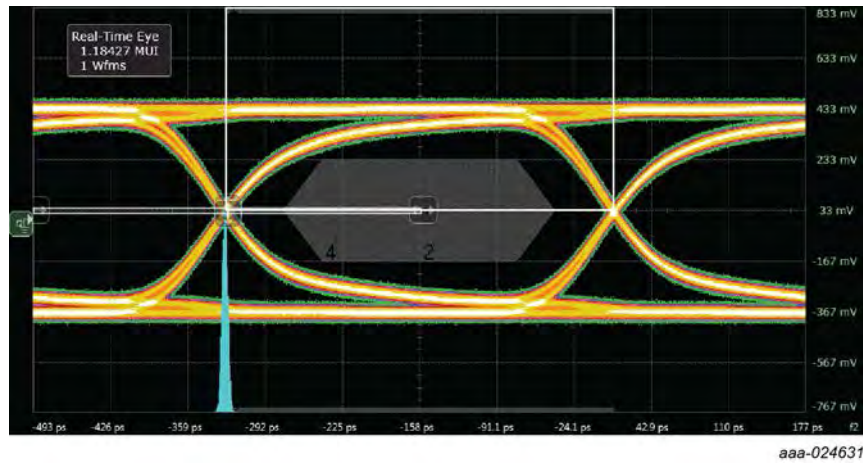
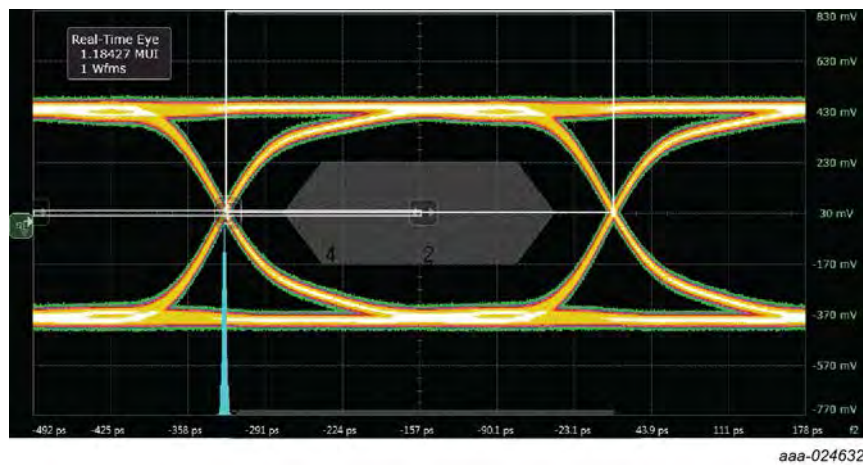


Fig 4. Differential Time Domain Reflectometer (TDR) plot; typical values



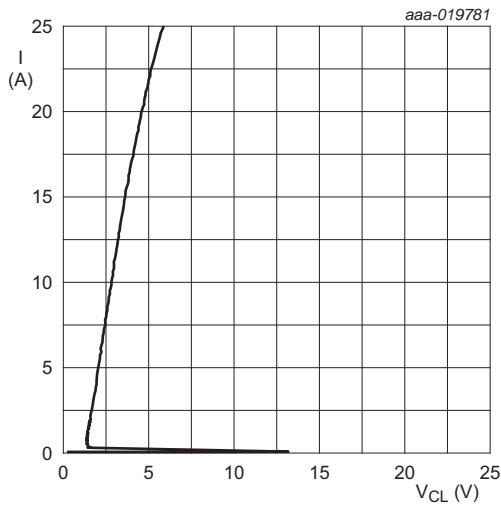
Pixel clock: 297 MHz
 Vertical scale: 200 mV/div
 Horizontal scale: 67 ps/div
 Offset: 33.4 mV

Fig 5. HDMI1.4 eye diagram, test board with PCMF2HDMI14S; typical values



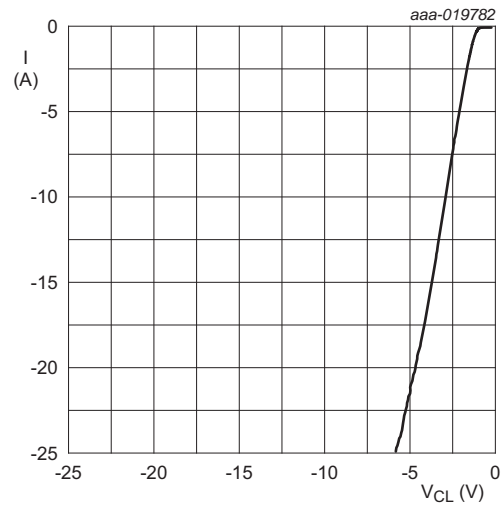
Pixel clock: 297 MHz
 Vertical scale: 200 mV/div
 Horizontal scale: 67 ps/div
 Offset: 29.6 mV

Fig 6. HDMI1.4 eye diagram, test board without device; typical values



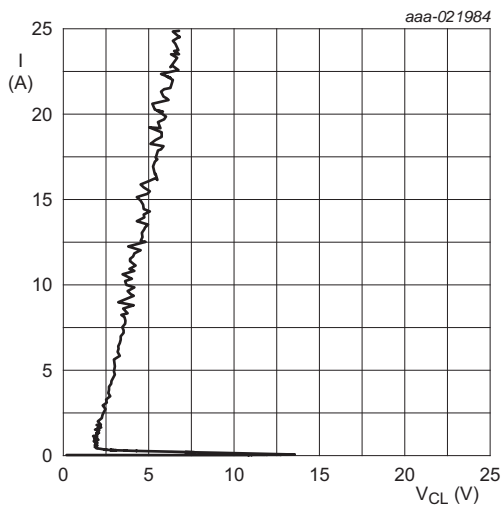
Transmission Line Pulse (TLP) = 100 ns;
 $t_r = 1$ ns

Fig 7. Dynamic resistance with positive clamping; typical values



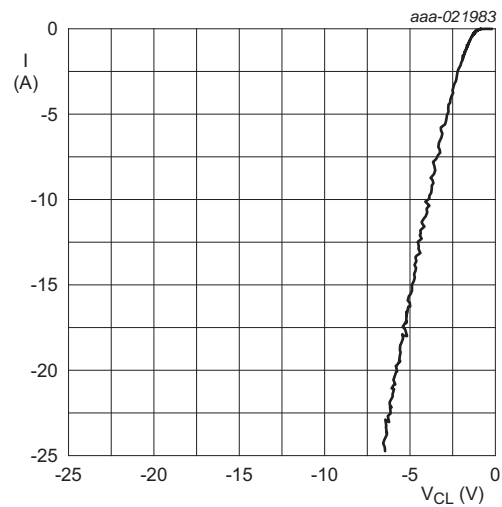
Transmission Line Pulse (TLP) = 100 ns;
 $t_r = 1$ ns

Fig 8. Dynamic resistance with negative clamping; typical values



Very-Fast Transmission Line Pulse (VF-TLP) = 5 ns;
 $t_r = 600$ ps

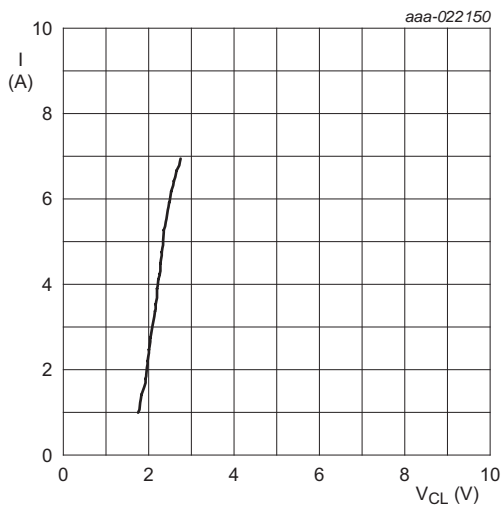
Fig 9. Dynamic resistance with positive clamping; typical values



Very-Fast Transmission Line Pulse (VF-TLP) = 5 ns;
 $t_r = 600$ ps

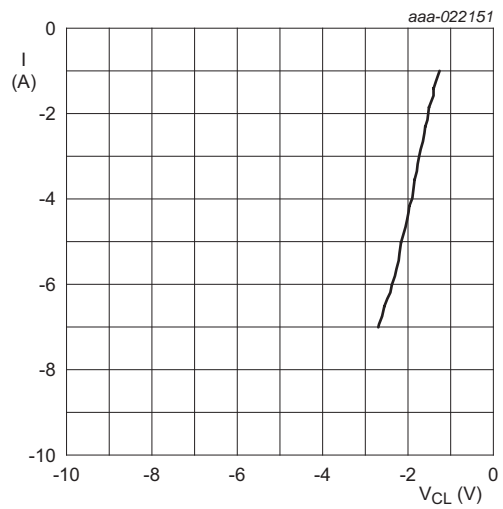
Fig 10. Dynamic resistance with negative clamping; typical values

The device uses an advanced clamping structure showing a negative dynamic resistance. This snapback behavior strongly reduces the clamping voltage to the system behind the ESD protection during an ESD event. Do not connect unlimited DC current sources to the data lines to avoid keeping the ESD protection device in snapback state after exceeding breakdown voltage (due to an ESD pulse for instance).



According to IEC 61000-4-5 (8/20 μ s)

Fig 11. Dynamic resistance with positive clamping; typical values



According to IEC 61000-4-5 (8/20 μ s)

Fig 12. Dynamic resistance with negative clamping; typical values

7. Application information

The device is designed to provide high-level ESD protection and common-mode filtering for differential high-speed data line pairs such as:

- HDMI 1.4
- Transition-Minimized Differential Signaling (TMDS)
- DisplayPort
- external Serial Advanced Technology Attachment (eSATA)
- Low Voltage Differential Signaling (LVDS)

When designing the PCB, give careful consideration to impedance matching and signal coupling. Do not connect the protected signal lines to unlimited current sources like, for example, a battery.

8. Package outline

WLCSP5: wafer level chip-size package; 5 bumps (2-1-2)

PCMF1HDMI14S

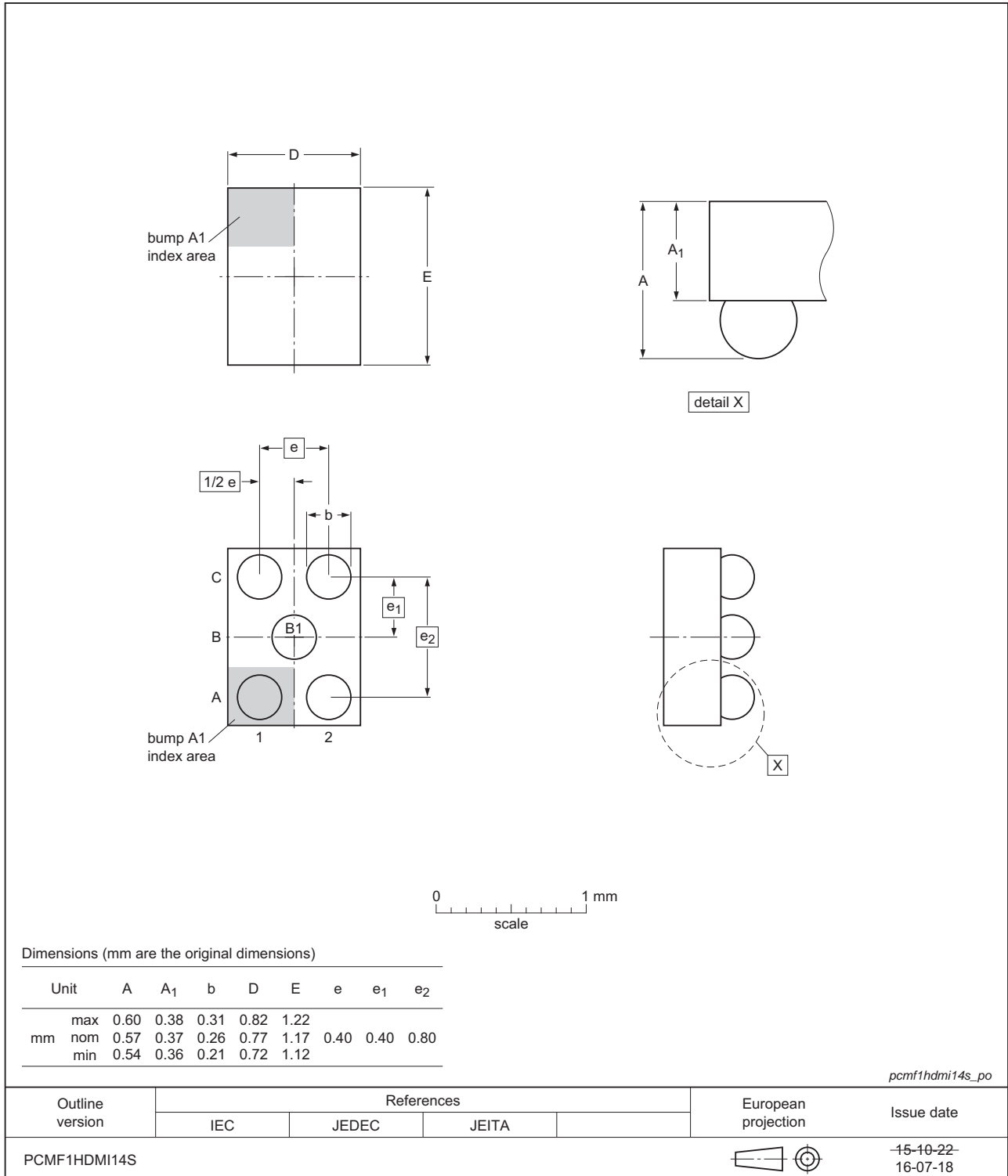


Fig 13. Package outline WLCSP5 (PCMF1HDMI14S)

WLCSP10: wafer level chip-size package; 10 bumps (4-2-4)

PCMF2HDMI14S

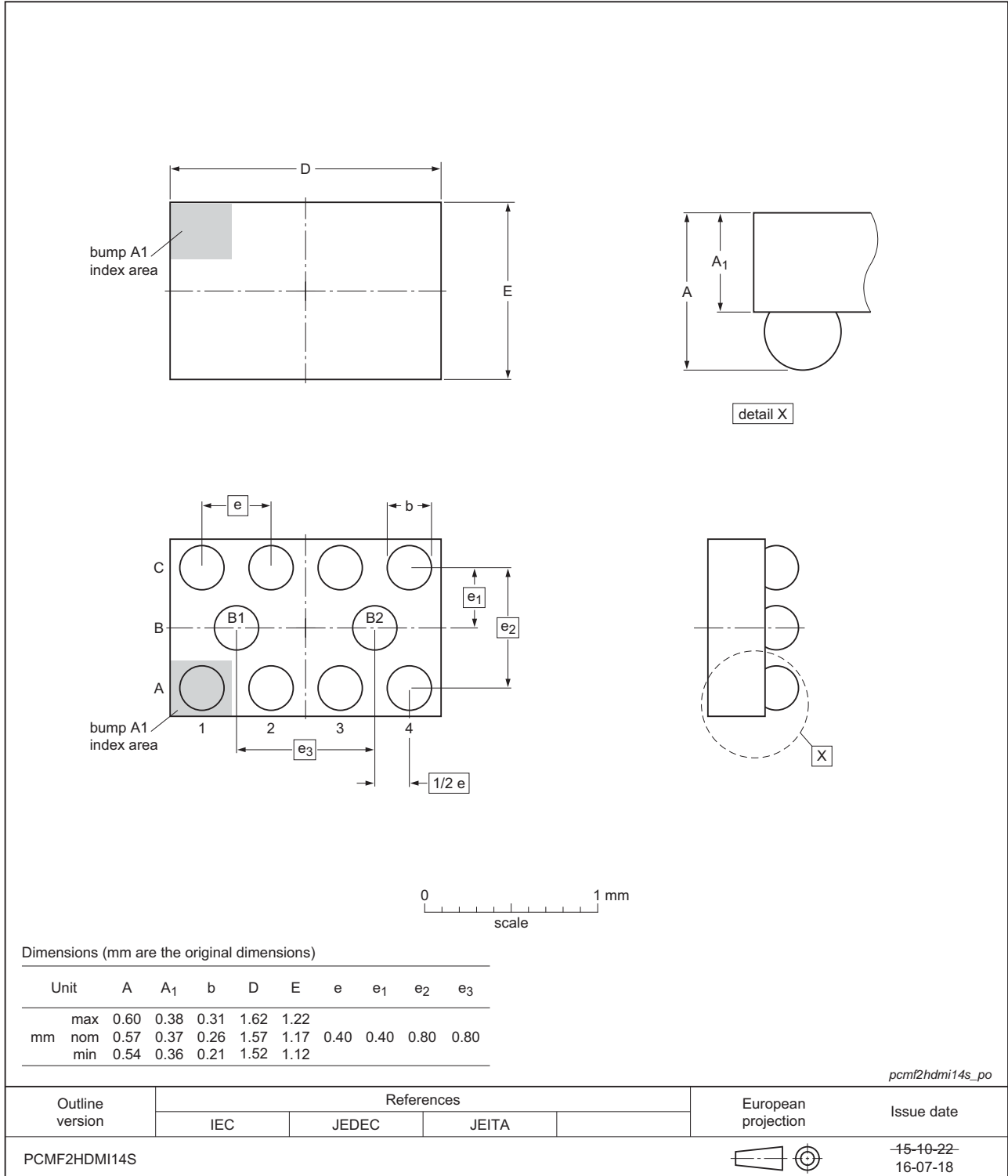


Fig 14. Package outline WLCSP10 (PCMF2HDMI14S)

WLCSP15: wafer level chip-size package; 15 bumps (6-3-6)

PCMF3HDMI14S

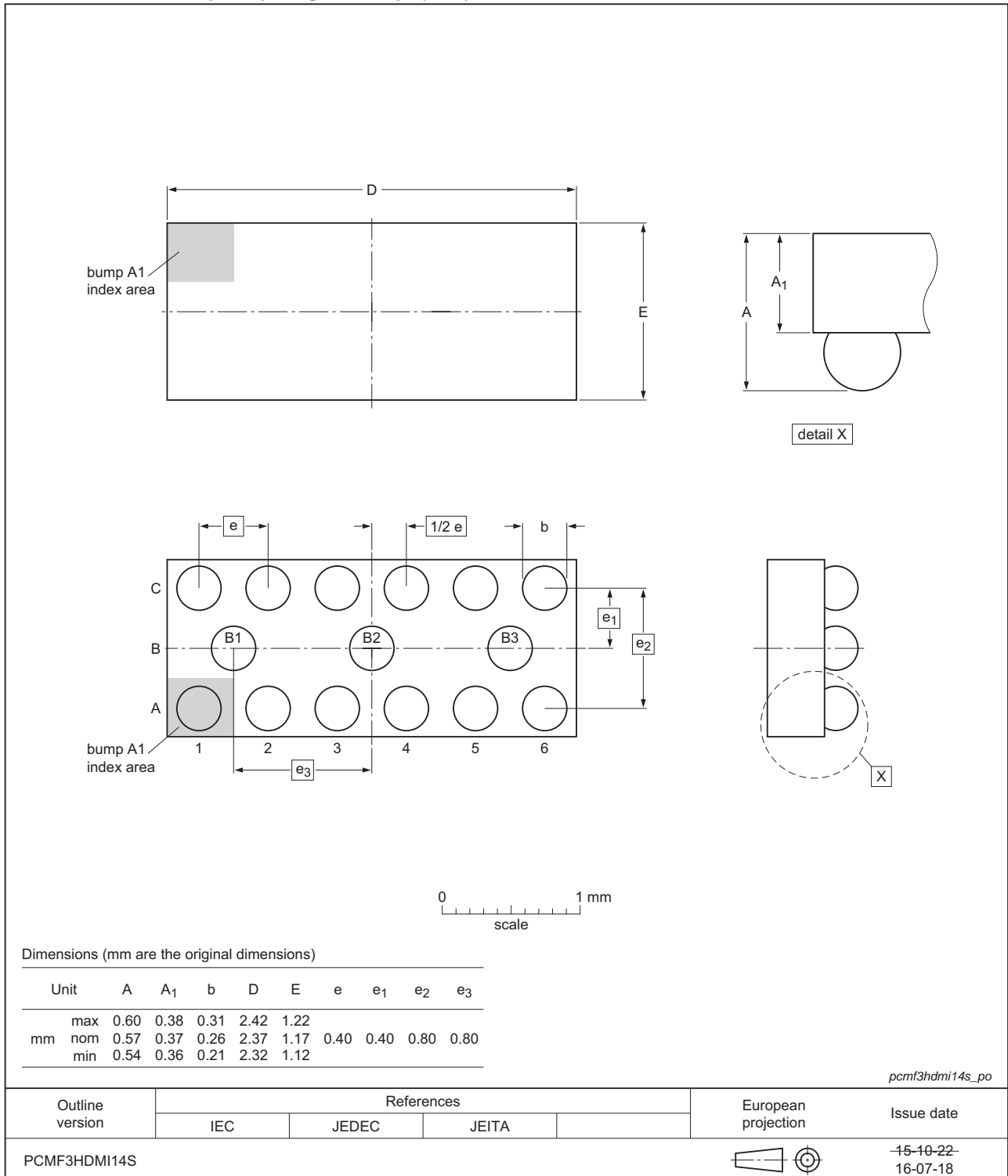


Fig 15. Package outline WLCSP15 (PCMF3HDMI14S)

9. Soldering

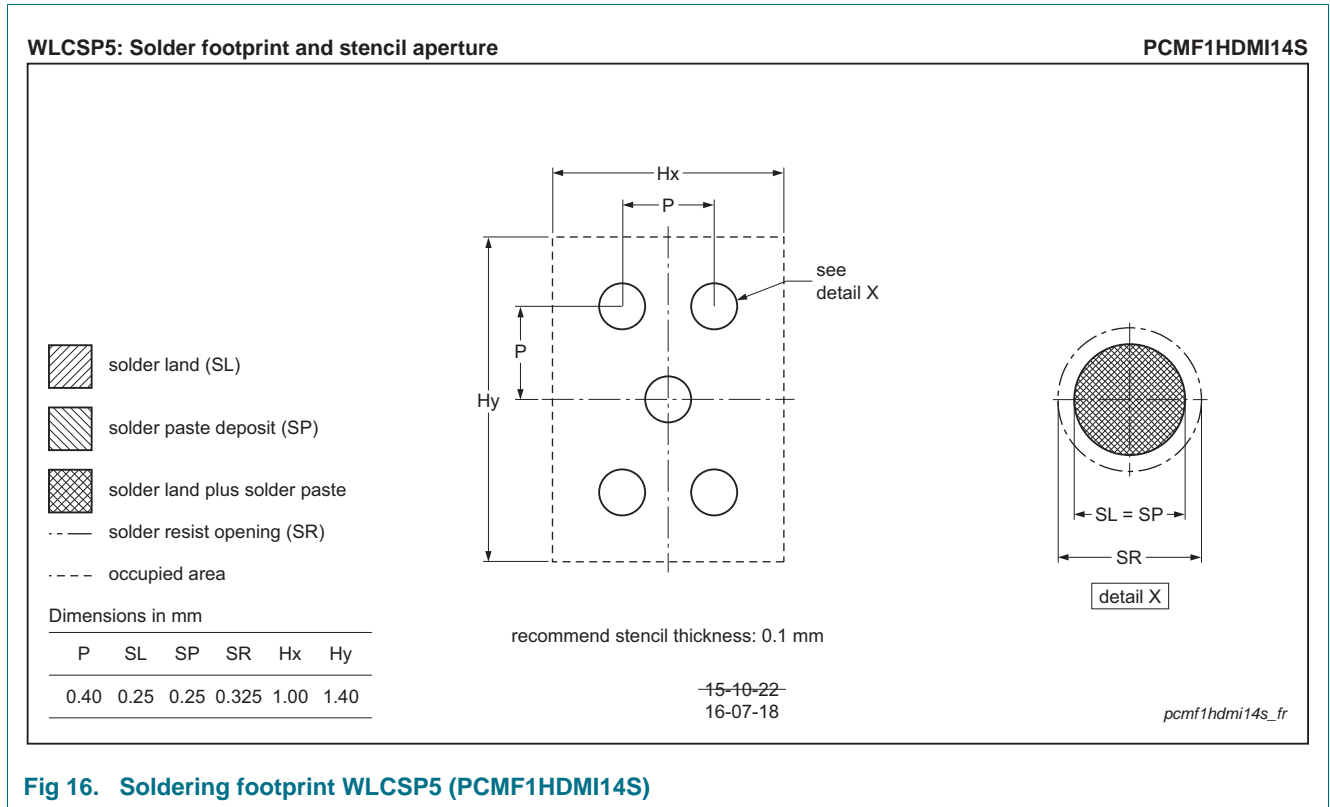


Fig 16. Soldering footprint WLCSP5 (PCMF1HDMI14S)

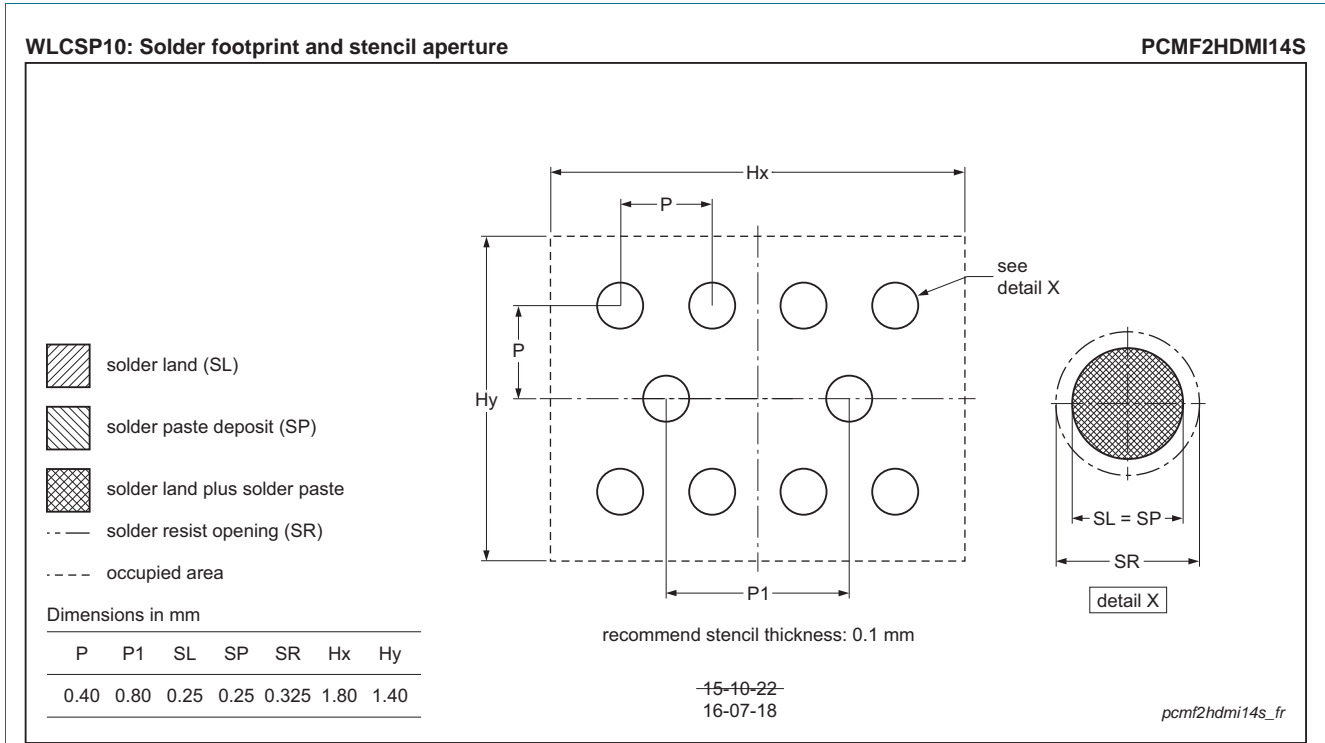


Fig 17. Soldering footprint WLCSP10 (PCMF2HDMI14S)

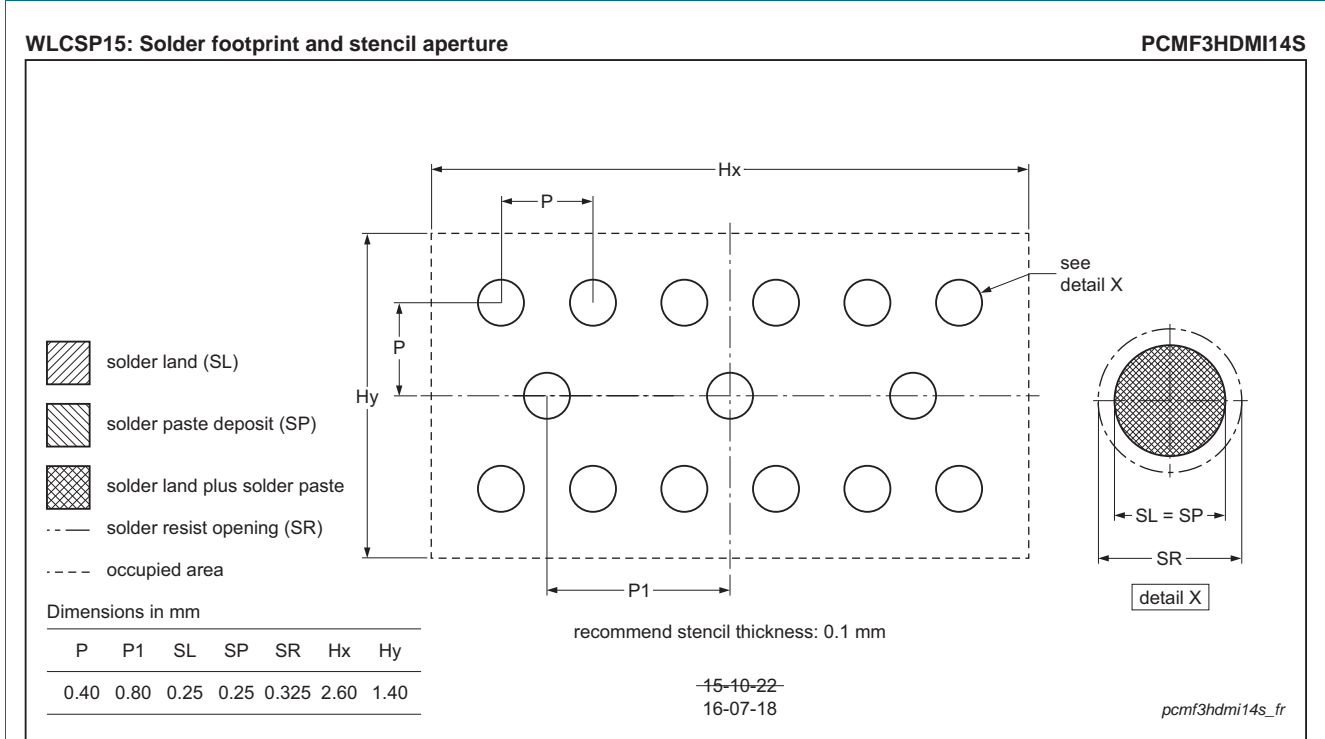


Fig 18. Soldering footprint WLCSP15 (PCMF3HDMI14S)

10. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PCMFXHDMI14S_SER v.2	20160915	Product data sheet	-	PCMFXHDMI14S_SER v.1
Modifications:	<ul style="list-style-type: none">• Fig 4 and Fig 5: eye diagrams added• Product status changed			
PCMFXHDMI14S_SER v.1	20160721	Preliminary data sheet	-	-

11. Legal information

11.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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13. Contents

1	Product profile	1
1.1	General description	1
1.2	Features and benefits	1
1.3	Applications	1
2	Pinning information	2
3	Ordering information	3
4	Marking	3
5	Limiting values	3
6	Characteristics	4
6.1	Channel characteristics	4
6.2	Frequency characteristics	4
7	Application information	9
8	Package outline	10
9	Soldering	13
10	Revision history	15
11	Legal information	16
11.1	Data sheet status	16
11.2	Definitions	16
11.3	Disclaimers	16
11.4	Trademarks	17
12	Contact information	17
13	Contents	18

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